

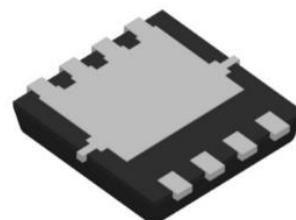
SSC8031GN4

P-Channel Enhancement Mode MOSFET

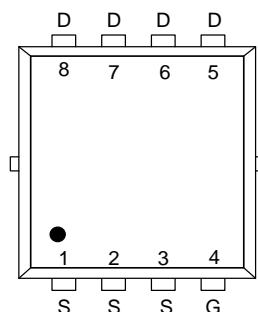
➤ Features

V _{DS}	V _{GS}	R _{DSON} (Typ.)	I _D
-30V	±20V	9mΩ@-10V	-54A
		12mΩ@-4V5	

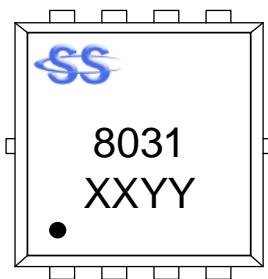
➤ Pin configuration



PDFN3.3X3.3-8L (Bottom View)



Pin Configuration (Top View)



Marking

(XXYY: Internal Traceability Code)

➤ Ordering Information

Device	Package	Shipping
SSC8031GN4	PDFN3.3X3.3-8L	5000/Reel

➤ Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Ratings	Unit
V_{DSS}	Drain-to-Source Voltage	-30	V
V_{GSS}	Gate-to-Source Voltage	± 20	V
I_D	Continuous Drain Current ^d	$T_C=25^\circ\text{C}$	-54
		$T_C=100^\circ\text{C}$	-30
I_{DSM}	Continuous Drain Current ^a	$T_A=25^\circ\text{C}$	-14.7
		$T_A=70^\circ\text{C}$	-10.8
I_{DM}	Pulsed Drain Current ^b	-200	A
P_D	Power Dissipation ^c	$T_C=25^\circ\text{C}$	41
		$T_C=100^\circ\text{C}$	16.7
P_{DSM}	Power Dissipation ^a	$T_A=25^\circ\text{C}$	3.13
		$T_A=70^\circ\text{C}$	2
I_{AS}	Avalanche Current ^b L=0.5mH Single Pulse	-18	A
E_{AS}	Avalanche Energy ^b L=0.5mH Single Pulse	81	mJ
T_J	Operation junction temperature	-55~150	$^\circ\text{C}$
T_{STG}	Storage temperature range	-55~150	

➤ Thermal Resistance Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Ratings	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance ^a	40	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Junction-to-Case Thermal Resistance	3	

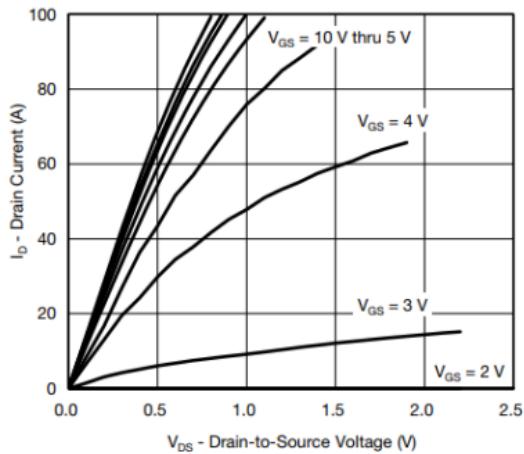
Note:

- a. The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2oz.copper, in a still air environment with $T_A=25^\circ\text{C}$. The value in any given application depends on the user's specific board design. The power dissipation is based on the $t \leq 10\text{s}$ thermal resistance rating.
- b. Repetitive rating, pulse width limited by junction temperature.
- c. The power dissipation P_D is based on $T_{J(MAX)}=150^\circ\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- d. The maximum current rating is package limited.

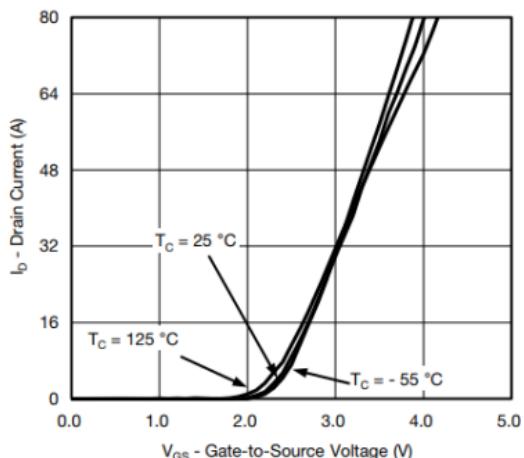
➤ Electrical Characteristics ($T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-30			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	-1	-1.7	-3	V
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = -10V, I_D = -10A$		9	12	$m\Omega$
		$V_{GS} = -4.5V, I_D = -7A$		12	17	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -30V, V_{GS} = 0V$			1	μA
Gate-Source Leak Current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$			± 100	nA
Transconductance	G_{FS}	$V_{DS} = -5V, I_D = -10A$		18		s
Forward Voltage	V_{SD}	$V_{GS} = 0V, I_S = -1A$		-0.7	-1.4	V
Gate Resistance	R_G	$V_{DS} = 0V, f = 1MHz$		9		Ω
Input Capacitance	C_{ISS}	$V_{DS} = -20V, V_{GS} = 0V,$ $f = 1MHz$		2000		pF
Output Capacitance	C_{OSS}			210		
Reverse Transfer Capacitance	C_{RSS}			138		
Total Gate Charge	Q_G	$V_{GS} = -4.5V, V_{DS} = -15V,$ $I_D = -7A$		24		nC
Gate to Source Charge	Q_{GS}			8		
Gate to Drain Charge	Q_{GD}			12		
Turn-on Delay Time	$T_{D(ON)}$	$V_{GS} = -10V, V_{DS} = -15V,$ $R_L = 1.5\Omega, R_G = 3\Omega$		8.6		ns
Rise Time	T_r			7		
Turn-off Delay Time	$T_{D(OFF)}$			39		
Fall Time	T_f			10		

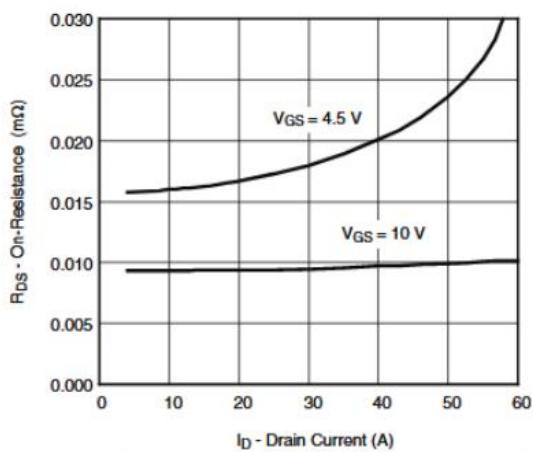
➤ Typical Performance Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)



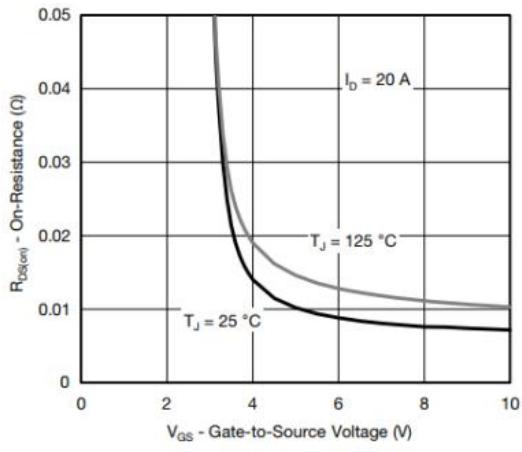
Output Characteristics



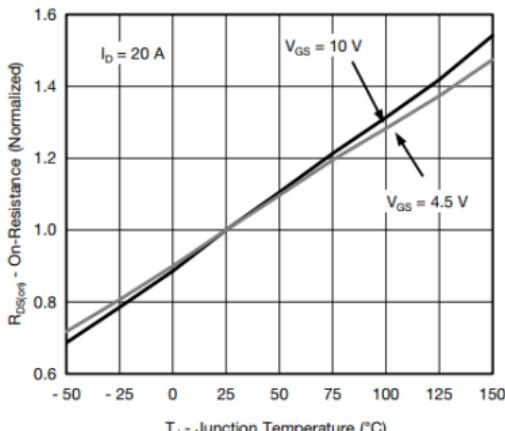
Transfer Characteristics



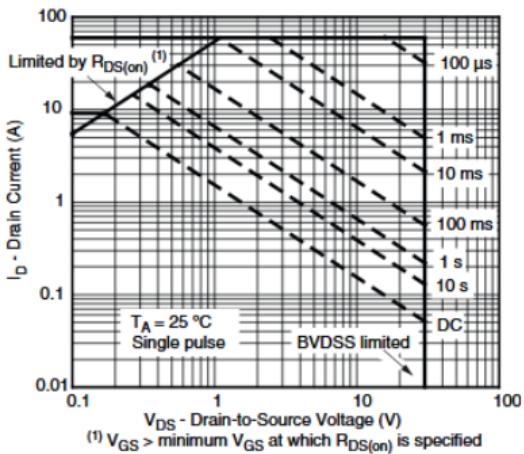
On-Resistance vs. Drain Current and Gate Voltage



On-Resistance vs. Gate-to-Source Voltage

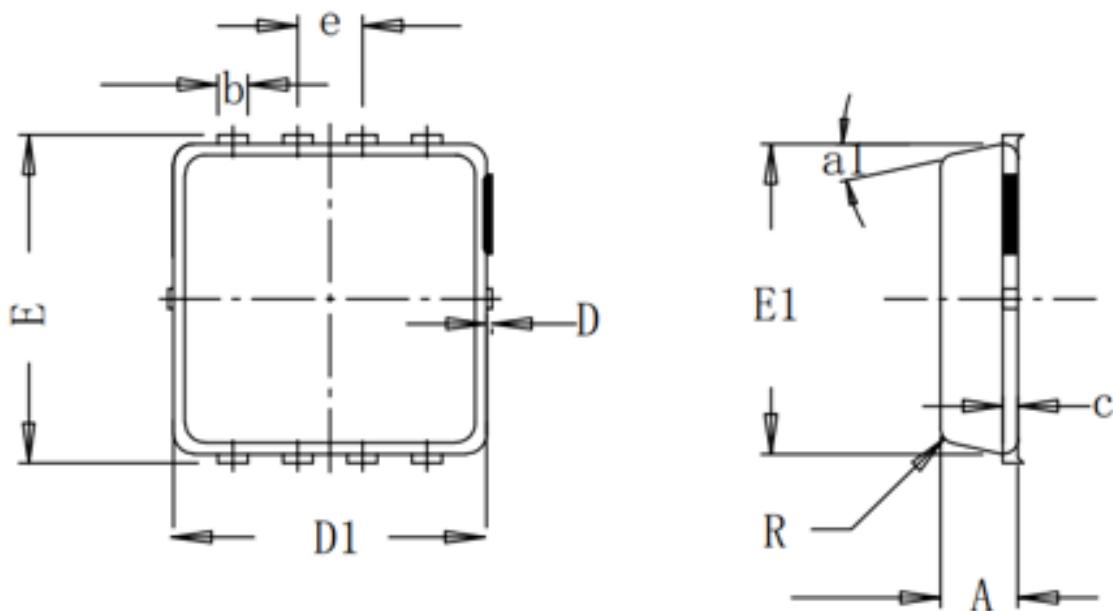


On-Resistance vs. Junction Temperature



Safe Operating Area, Junction-to-Ambient

➤ Package Information



Symbol	Dimensions In Millimeters		
	Min.	Nom.	Max.
A	0.75	0.78	0.81
b	0.297	0.3	0.35
c	-	0.152	-
D	0	0.05	0.1
D1	3.12	3.15	3.18
D2	-	2.35	-
E	3.2	3.3	3.4
E1	3.09	3.12	3.15
E2	-	1.75	-
E3	-	0.575	-
E4	-	0.4	-
R	-	0.15	-
e	0.65BSC		
a1°	-	12°	-

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